

shall not be construed as a representation or warranty regarding the proper EECN or HTS classification of any item at the time of export.

Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, etc.) for functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission (SEC) as meaning that the product does not contain any minerals (tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of minerals before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html> for information on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved under certain conditions. See [Intel Turbo Boost Technology](#) for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types. RCP represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not used in a system.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and must meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The PCB / substrate must also meet RoHS requirements.

For benchmarking data see <http://www.intel.com/performance>.

Intel processor numbers are not a measure of performance. Processor numbers differentiate product offerings. For more information, see <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture operating system.



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